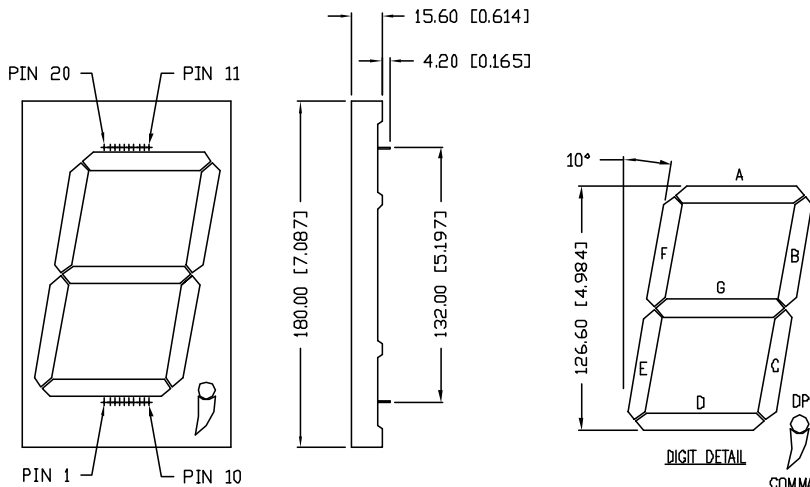


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ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=10\text{mA}$

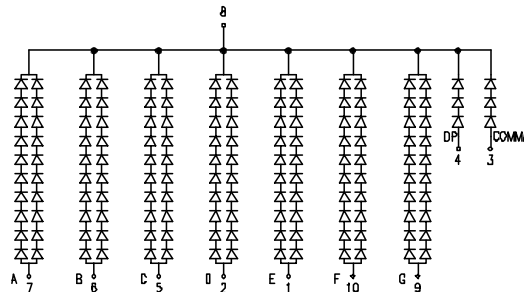
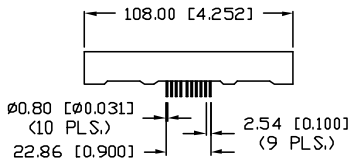
| PARAMETER | MIN | TYP | MAX | UNITS | TEST COND |
|------------------|----------------------|-----------|---------|----------------|----------------------|
| PEAK WAVELENGTH | | 635 (RED) | | nm | |
| FORWARD VOLTAGE* | | 21/6.3* | 24/7.2* | V_f | |
| REVERSE VOLTAGE | 25 | | | V_r | $I_f=100\mu\text{A}$ |
| AXIAL INTENSITY | | 9000 | | μcd | $I_f=10\text{mA}$ |
| EMITTED COLOR: | RED | | | | |
| FACE COLOR: | GREY | | | | |
| SEGMENT COLOR: | MILKY WHITE DIFFUSED | | | | |

* SECOND VALUE FOR DECIMAL POINT AND COMMA.

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

| PARAMETER | COLORS | MAX | UNITS |
|--------------------------|--------|------------|------------|
| PEAK FORWARD CURRENT* | | 80 | mA |
| STEADY CURRENT | | 12 | mA |
| POWER DISSIPATION | | 60 | mW |
| DERATE FROM 25°C | | -1.2 | mW/°C |
| OPERATING, STORAGE TEMP. | | -40 TO +85 | °C |
| SOLDERING TEMP. | | +260 | °C |
| 2.0mm FROM BODY | | | 3 SEC. MAX |

* $t < 10\mu\text{s}$



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.030), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION MAX= +0.00 -DECIMAL PRECISION

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5.0" SINGLE DIGIT SEVEN SEGMENT DISPLAY,
635nm RED CHIPS, GRAY FACE,
MILKY WHITE DIFFUSED SEGMENTS, COMMON CATHODE.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JD
CHECKED BY:
APPROVED BY:
DATE: 11.29.04
PAGE: 1 OF 1
SCALE: N/A